

MAKING ELECTRICAL CONNECTIONS BETWEEN
A CIRCUIT BOARD AND AN INTEGRATED CIRCUIT

Abstract of the Disclosure

A socket may receive both ball grid and land grid array packages. Thus, in some embodiments, the early package prototypes, without solder balls, may be packaged
5 in the same socket design that is ultimately used for production devices using ball grid array packaging. Both land grid array and ball grid arrays may be self-centered on the socket in some embodiments. An S-shaped spring contact may be utilized to electrically connect to either
10 solder balls or lands in a wiping action.